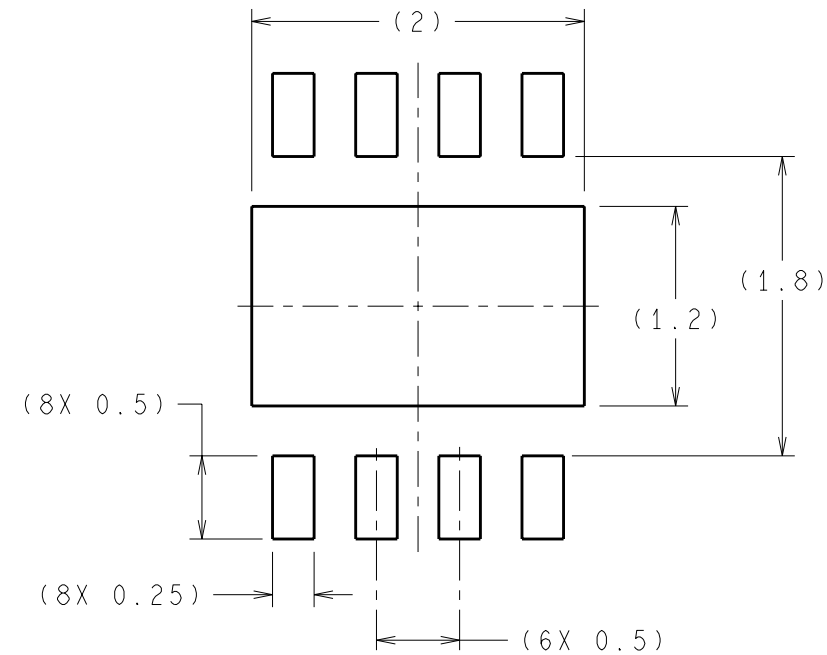
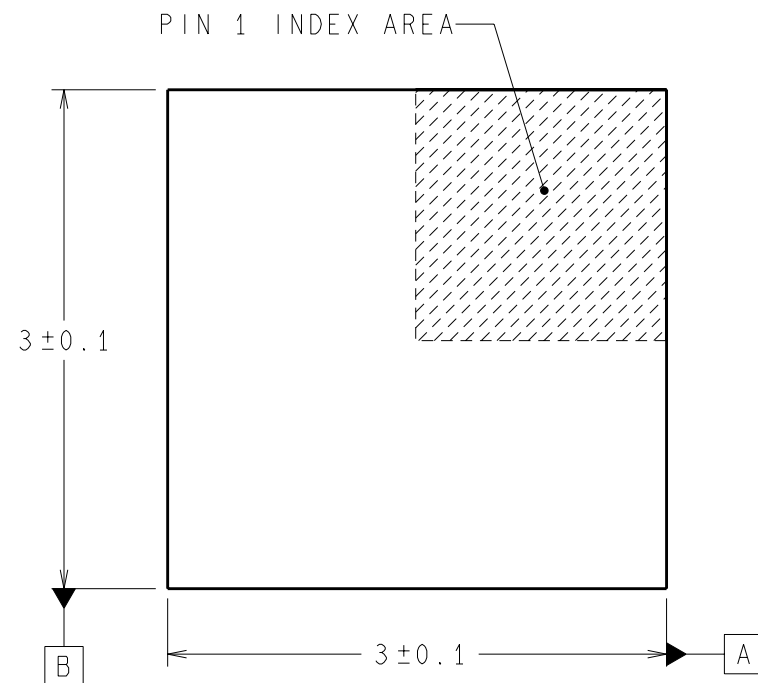
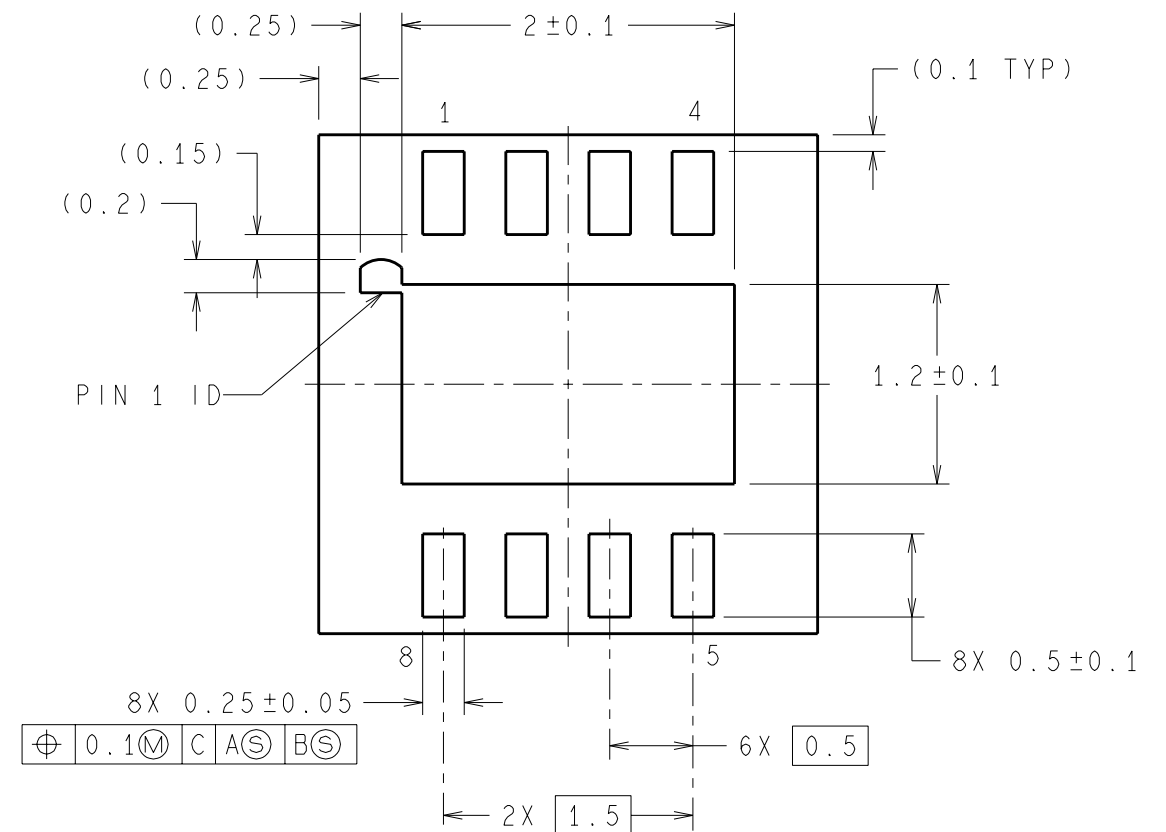
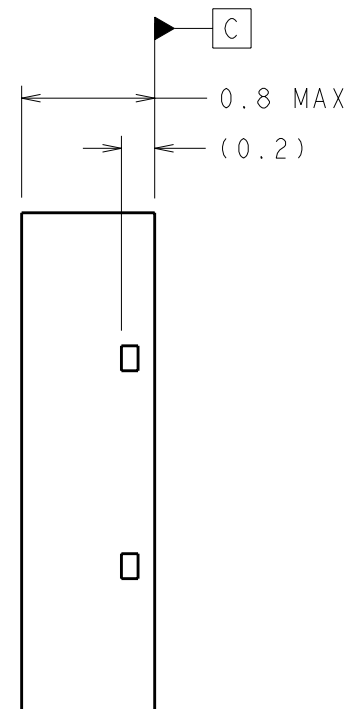




RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



DIMENSIONS ARE IN MILLIMETERS



NOTES: UNLESS OTHERWISE SPECIFIED.

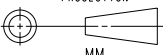
- STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM LEAD/TIN (SOLDER) ON COPPER.
- REFERENCE JEDEC REGISTRATION MO-229, VARIATION WEED-1.

REVISIONS

REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	122	05/30/2000	SN/TL/AL
B	CHG EXPOSED DAP LENGTH: 2.0 WAS 1.8; APPLY JEDEC REGISTRATION TO NOTE 2	366	10/05/2001	TE/TL/SM
C	ADD PIN 1 OD DIM'S; CHG FORMAT TO B SIZE	885	11/14/2002	TL/FL

Technical drawing of a component showing dimensions and tolerances:

- Overall width: 1
- Top-left corner radius: 4
- Top-right corner radius: (0.1 TYP)
- Central rectangular feature height: 1.2 ± 0.1
- Bottom-left corner radius: 5
- Bottom-right corner radius: 5
- Bottom edge width: 6 X 0.5
- Bottom edge length: 8 X 0.5 ± 0.1

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	NSANTHIRAN & TL	05/30/2000			
DFTG. CHK.	MARTA SUCHY	11/14/2002			
ENGR. CHK.	FELIX LI	11/14/2002			
PROJECTION				LLP, PLASTIC, DUAL, 3 X 3 X 0.75 mm BODY, 8 LD, 0.5 mm PITCH	
					
MM					
SCALE	SIZE	DRAWING NUMBER		REV	
NTS	B	(SC)MKT-LDA08A		C	
FORMERLY: N/A			SHEET 1 of 1		